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**\*\* CONTINUING DATA \*\*\*\*\***

This application is a DIV of 09/499,384 02/07/2000 PAT 6,724,084

**\*\* FOREIGN APPLICATIONS \*\*\*\*\***

JAPAN 11-029842 02/08/1999  
 JAPAN 11-033116 02/10/1999  
 JAPAN 11-040400 02/18/1999  
 JAPAN 11-051212 02/26/1999  
 JAPAN 11-265739 09/20/1999

**IF REQUIRED, FOREIGN FILING LICENSE GRANTED**

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Foreign Priority claimed	<input checked="" type="checkbox"/> yes <input type="checkbox"/> no	STATE OR COUNTRY JAPAN	SHEETS DRAWING 22	TOTAL CLAIMS 4	INDEPENDENT CLAIMS 3
35 USC 119 (a-d) conditions met	<input checked="" type="checkbox"/> yes <input type="checkbox"/> no <input type="checkbox"/> Met after Allowance				
Verified and Acknowledged	Examiner's Signature 	Initials			

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**TITLE**

Semiconductor chip and production thereof, and semiconductor device having semiconductor chip bonded to solid device

FILING FEE RECEIVED 770	FEES: Authority has been given in Paper No. _____ to charge/credit DEPOSIT ACCOUNT No. _____ for following:	<input type="checkbox"/> All Fees <input type="checkbox"/> 1.16 Fees ( Filing ) <input type="checkbox"/> 1.17 Fees ( Processing Ext. of time ) <input type="checkbox"/> 1.18 Fees ( Issue )
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